

LNJ012X8ARA1

High Bright Surface Mounting Chip LED

TSS Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	65	mW
Forward current	I_F	15	mA
Pulse forward current *	I_{FP}	55	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

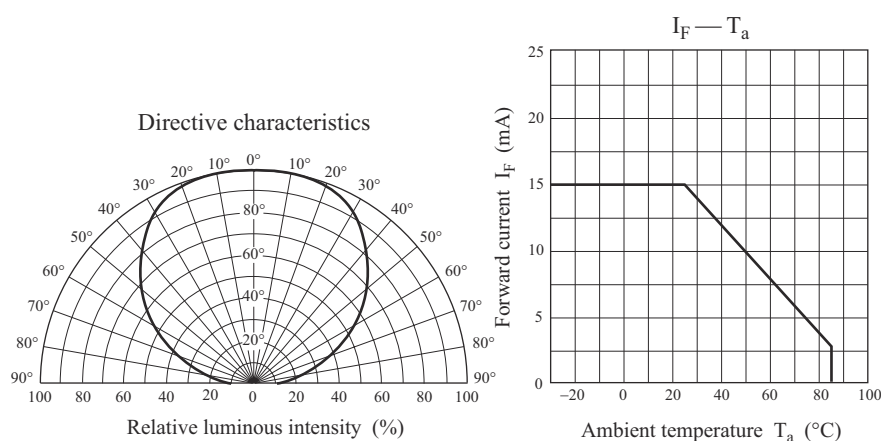
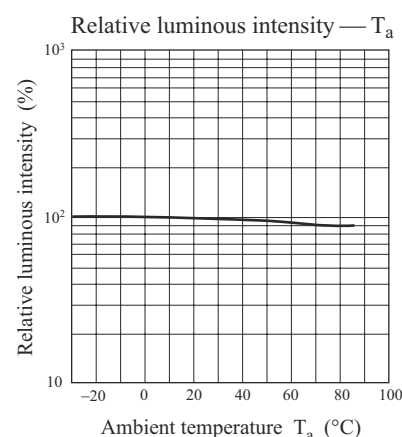
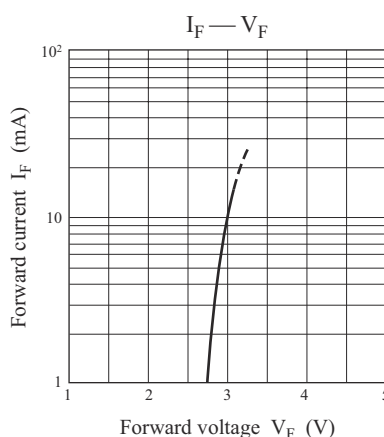
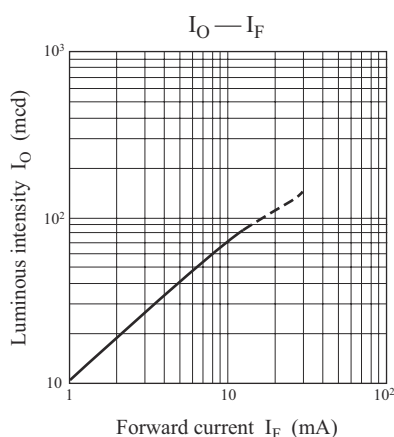
- White

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

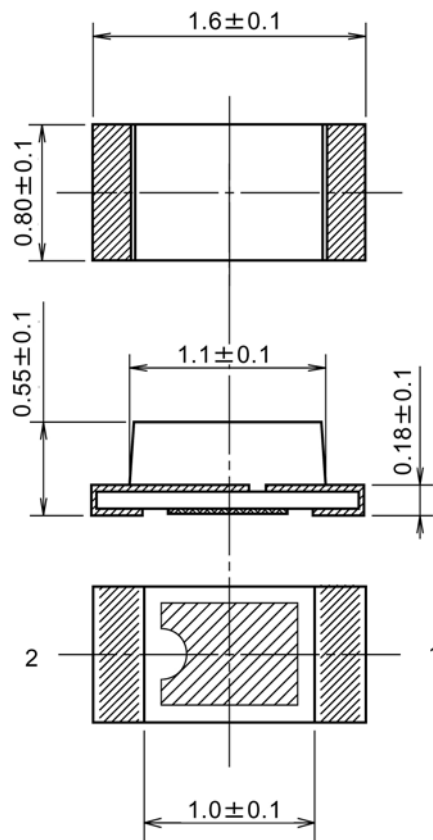
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *	I_O	$I_F = 5 \text{ mA}$	24	40	122	mcd
Reverse current	I_R	$V_R = 5 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 5 \text{ mA}$		2.90	3.20	V
Chromaticity coordinates	x	$I_F = 5 \text{ mA}$	0.258	0.300	0.337	—
	y	$I_F = 5 \text{ mA}$	0.252	0.300	0.350	—

Note) *: Measurement tolerance: $\pm 20\%$



■ Package (Unit: mm)

KLTFTN2K1200



- Pin name
 - 1: Anode
 - 2: Cathode

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